

Title: Thermally Conductive Coating Composition  
Honeywell Docket No.: H0003298 (4962)  
Riordan Docket No.: 52-020-001

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#### ABSTRACT

A thermal interface composition is described herein that includes: a) at least two siloxane-based compounds; b) at least one inorganic micro-filler material; and c) at least one thermally conductive filler material. Additionally, a method of forming a thermal interface material is disclosed herein that includes: a) providing at least two siloxane-based compounds; b) providing at least one inorganic micro-filler material; c) providing at least one thermally conductive filler material; and d) combining the at least two siloxane-based compounds, the at least one inorganic micro-filler material and the at least one thermally conductive filler material.